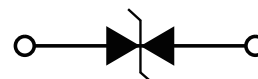
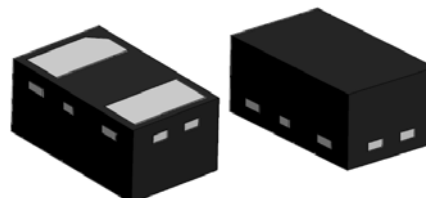


Features

- ◇ Small Body Outline Dimensions
- ◇ Low Body Height
- ◇ Peak Power up to 150 Watts @ 8 x 20 μ s Pulse
- ◇ Low Leakage current
- ◇ Response Time is Typically <1 ns
- ◇ ESD Rating of Class 3 (>16 kV) per Human Body Model

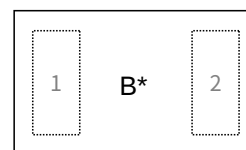
DFN1006



Package Outline

Applications

- ◇ Cellular phones
- ◇ Portable devices
- ◇ Digital cameras
- ◇ Power supplies



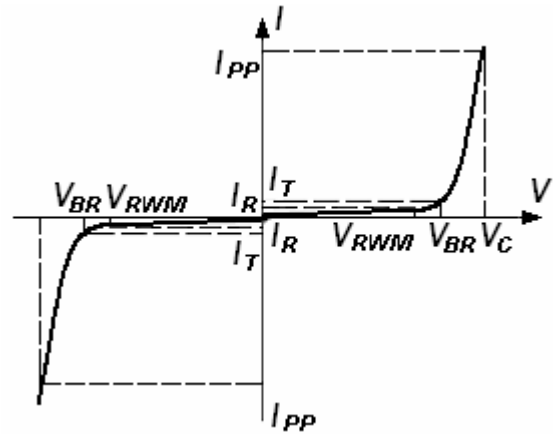
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Maximum Ratings (Ta = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	100	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	± 20 ± 20
	IEC61000-4-4 (EFT)		40
	ESD Voltage	Per Human Body Model	16
			KV

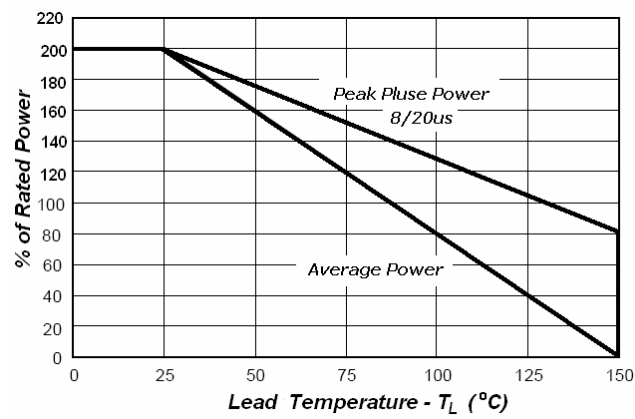
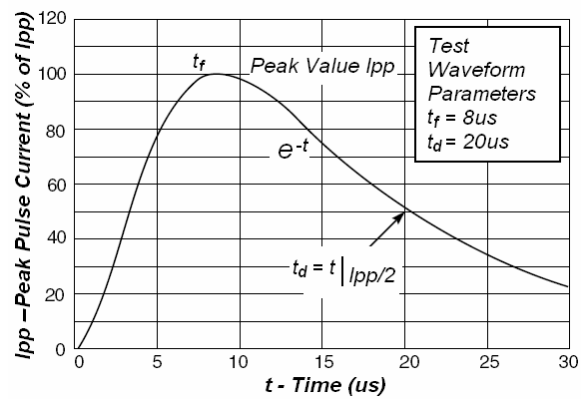
Portion Electronics Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

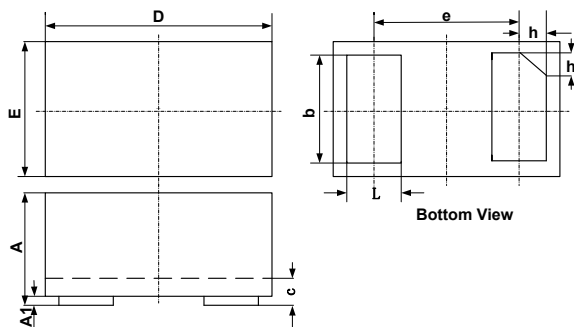


Device	V_{RWM} (V)	$I_R(\mu A)$ @ V_{RWM}	V_{BR} (V)@ I_T (Note 1)	I_T	V_C (V) @ $I_{PP}=6 A^*$	V_C (V) @ Max I_{PP}^*	I_{PP} (A)*	P_{PK} (W)*	C (pF)
	Max	Max	Min	mA	Typ	Max	Max	Max	Typ
ESD8D3.3C	3.3	1	4.5	1.0	10	13	8	100	15

Typical Characteristics

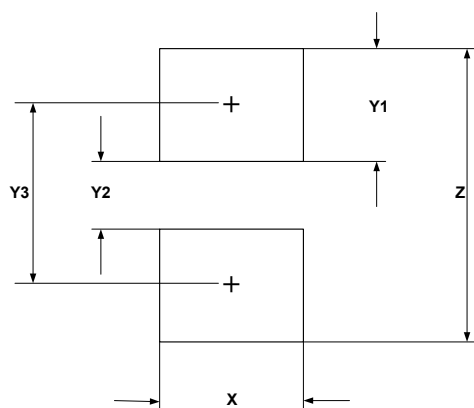


DFN1006-2L Package Outline Drawing



SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
c	0.12	0.15	0.18	0.005	0.006	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65 BSC			0.026 BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012
h	0.07	0.12	0.17	0.003	0.005	0.007

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
X	0.60	0.024
Y1	0.50	0.020
Y2	0.30	0.012
Y3	0.80	0.032
Z	1.30	0.052